General Description

The SJ60P110 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as -4.5V. This device is suitable for use as a wide variety of applications.

Features

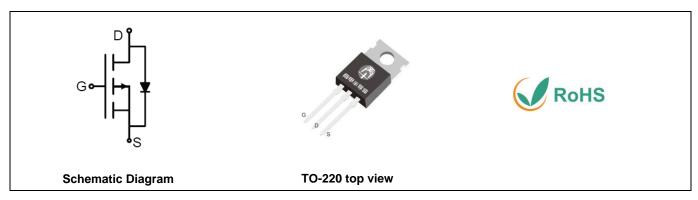
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

Application

Load Switch

Key Performance Parametes

Parameter	Value	Unit
V _{DS}	-60	V
R _{DS(ON)_TYP}	10.4	mΩ
I _D	-64	A
Q _G	140	nC



Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJ60P110	SJ60P110	TO-220	Tube	\	\	1000 Pcs

Table 1. Absolute Maximum Ratings (T_C=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	-60	V
V _{GS}	Gate-Source Voltage (V _{DS} =0V)	±20	V
1-	Drain Current-Continuous(Tc=25℃)		А
I _D	Drain Current-Continuous(T _C =100℃)	-41	А
IDM (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	-256	А
D	Maximum Power Dissipation(T _C =25°ℂ)	96	W
P _D	Maximum Power Dissipation(Tc=100°C)	38	W
Eas	Avalanche energy (Note 2)	484	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	C

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
R _θ JC	Thermal Resistance, Junction-to-Case		1.3	°C/W

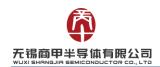


Table 3. Electrical Characteristics (T_J=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =-250μA	-60			V
	7 0 1 1/1 5 1 0 1	V _{DS} =-60V, V _{GS} =0V T _J =25°C			-1	μΑ
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-60V, V _{GS} =0V T _J =125°C			-100	μΑ
Igss	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1		-2.5	V
g FS	Forward Transconductance	V _{DS} =-5V, I _D =-20A		38		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-15A T _J =25℃		10.4	13.5	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-4.5V, I _D =-10A T _J =25°C		14	18.6	mΩ
Dynamic Chara	acteristics					
Ciss	Input Capacitance			8700		pF
Coss	Output Capacitance	V _{DS} =-30V,V _{GS} =0V, f=1.0MHz		290		pF
Crss	Reverse Transfer Capacitance			210		pF
Switching Para	meters					
t _{d(on)}	Turn-on Delay Time			26		nS
tr	Turn-on Rise Time	V _{GS} =-10V, V _{DS} =-30V,		21		nS
$t_{d(off)}$	Turn-Off Delay Time	R _L =1.5Ω, R _{GEN} =3Ω		138		nS
tf	Turn-Off Fall Time			30		nS
Qg	Total Gate Charge			140		nC
Q _{gs}	Gate-Source Charge	V _{GS} =-10V, V _{DS} =-30V, I _D =-20A		19		nC
Q_{gd}	Gate-Drain Charge			28		nC
Source-Drain D	Diode Characteristics					
I _{SD}	Source-Drain Current (Body Diode)				-64	Α
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =-20A			-1.2	V
t _{rr}	Reverse Recovery Time	I _F =-20A, di/dt=100A/µs		56		ns
Q _{rr}	Reverse Recovery Charge	I _F =-20A, di/dt=100A/μs		63		nC

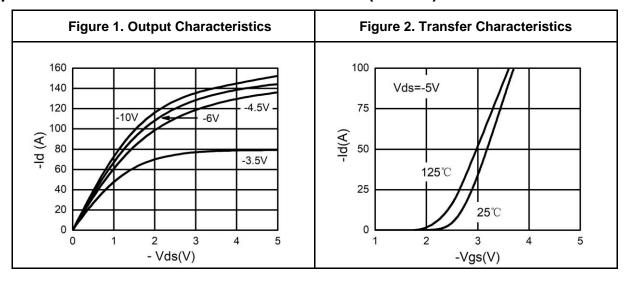
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

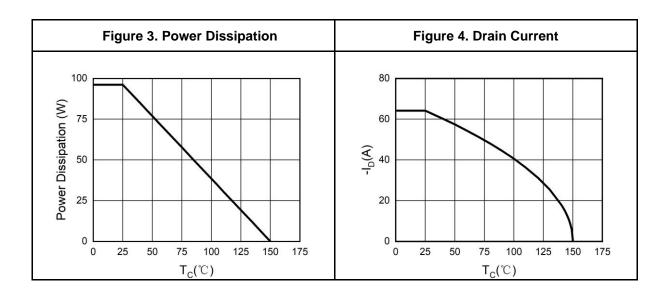
Notes 2.E_{AS} condition: $T_J=25^{\circ}\text{C}$, $V_{DD}=40\text{V}$, $V_{G}=-10\text{V}$, $Rg=25\Omega$, L=0.5mH.

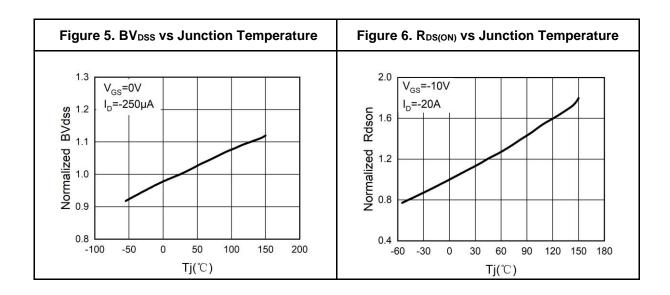
Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



Typical Electrical And Thermal Characteristics (Curves)

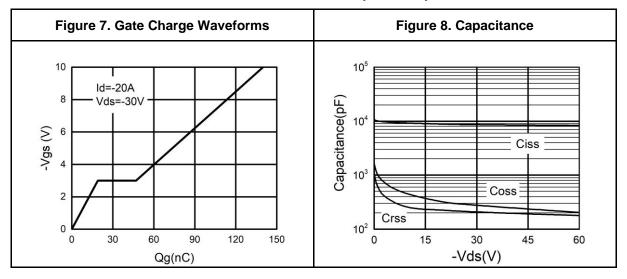


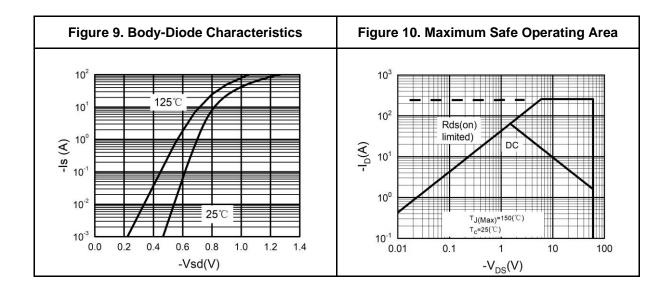






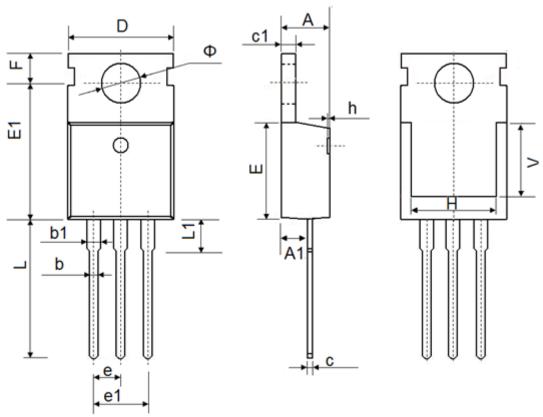
Typical Electrical And Thermal Characteristics (Curves)







TO-220 Package Information



Cumbal	Dimens	sions In Millimeters	Dim	ensions In Inches
Symbol	Min.	Max.	Min.	Max
Α	4.300	4.700	0.169	0.185
A1	2.200	2.600	0.087	0.102
b	0.700	0.950	0.028	0.037
b1	1.170	1.410	0.046	0.056
С	0.450	0.650	0.018	0.026
c1	1.200	1.400	0.047	0.055
D	9.600	10.400	0.378	0.409
Е	8.8500	9.750	0.348	0.384
E1	12.650	12.950	0.498	0.510
е	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
Н	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.750	14.300	0.502	0.563
L1	2.850	3.950	0.112	0.156
V	7.500	REF.	0.295 R	EF.
Ф	3.400	4.000	0.134	0.157

Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor.

The performances and characteristics of this product in the independent testing state are displayed in this document. Wuxi Shangjia Semiconductor can't guarantee of the performances and characteristics of this described product that mounted in the customer's products or equipments as same as that in the independent testing state. So the customer should evaluate and test devices mounted in the customer's products or equipments.

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